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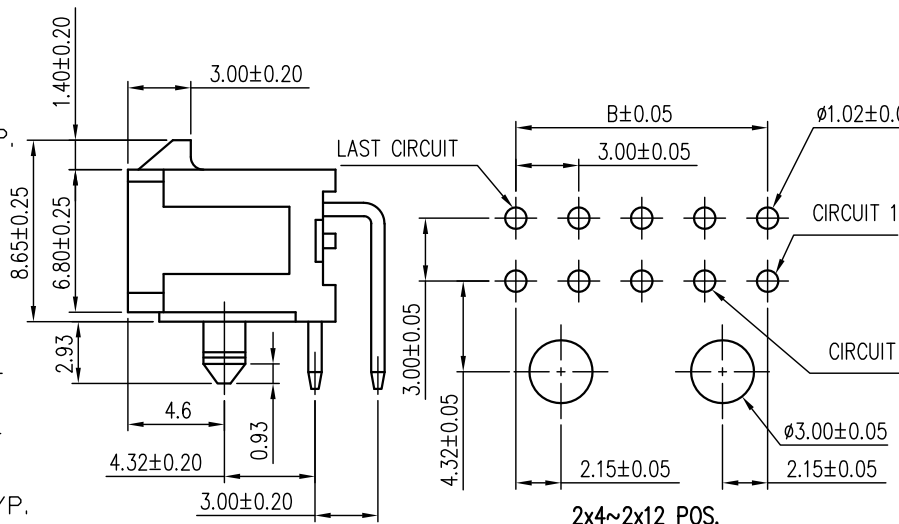
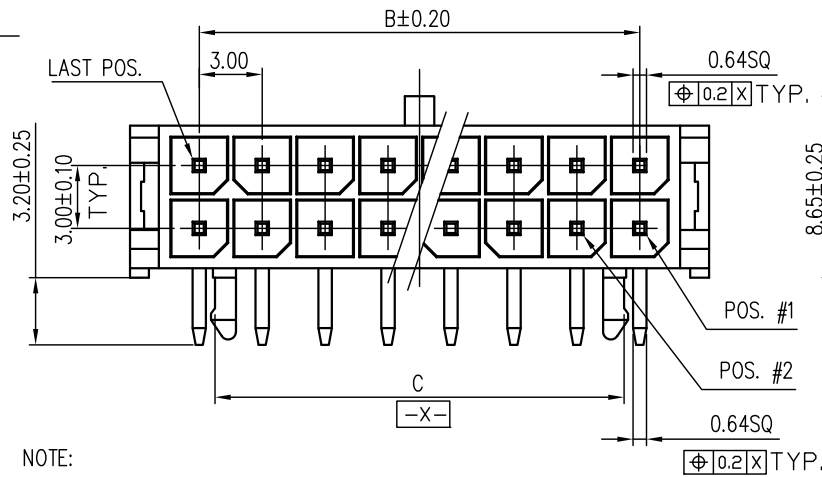
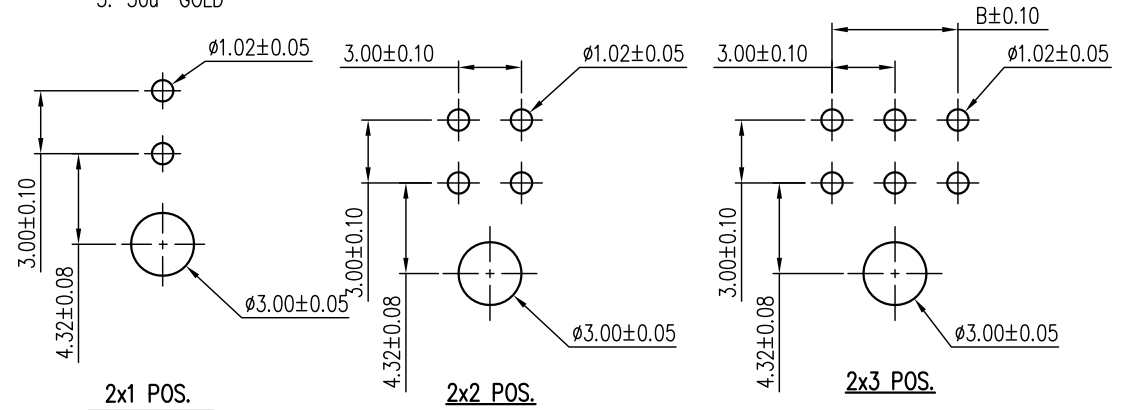
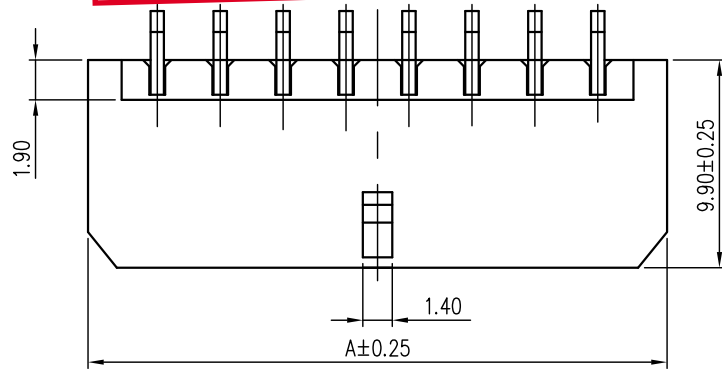
**PRELIMINARY RELEASE
SUBJECT TO CHANGE**

PART NO. G881AXX0X1TEU

No. of CIRCUIT — CONTACT FINISH

- 0: 100u" MATTE TIN PLATING (OVERALL)
- 1: GOLD FLASH (OVERALL)
- 2: 15u" GOLD
- 3: 30u" GOLD

REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A		RELEASE FOR RoHS	10/06/2005	Henry Ko
B	NE-11044	DRAWING UPDATE	03/28/2011	Arron Lin
C	NE-12011	ADDED DIM. 4.6 & 0.93	02/10/2012	Arron Lin
D	NE-13023	ADDED 30u" GOLD	01/31/2013	Arron Lin
EX1		ADDED DIM	07/22/2013	Arron Lin
EX2	EDSR#4667	ADDED 2PIN DRAWING AND UPDATE PACKING QUANTITY	01/08/2014	Arron Lin
EX3		UPDATE PACKING QUANTITY	03/03/2014	Arron Lin



24	39.60	33.00	31.50
22	36.60	30.00	28.50
20	33.60	27.00	25.50
18	30.60	24.00	22.50
16	27.60	21.00	19.50
14	24.60	18.00	16.50
12	21.60	15.00	13.50
10	18.60	12.00	10.50
08	15.60	9.00	7.50
06	12.60	6.00	2.80
04	9.60	3.00	2.80
02	6.60	NA	2.80
NO. OF CIRCUIT	A	B	C

- NOTE:
- INSULATOR: HIGH TEMP. THERMOPLASTIC, LCP, UL 94V-0, COLOR BLACK
 - CONTACT MATERIAL: COPPER ALLOY.
 - FINISH:
CONTACT AREA: SELECTIVE PLATING;
SOLDERING AREA: MATTE TIN PLATING OR GOLD PLATING;
UNDER PLATING: NICKEL PLATING 50 u" THICKNESS MIN. OVERALL.
 - THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EU FOR RoHS.
 - APPLICABLE P.C.BOARD THICKNESS: 1.60mm
 - PACKING MUST BE PER Amphenol PACKING SPECIFICATION

RECOMMENDED PCB LAYOUT

TOLERANCE	APPROVALS	DATE	TITLE		PART No.			
X. ±0.30	DRAWN Debby Hung	03/03/2014	G881A SERIES WIRE TO BOARD, WAFER 3.00 MM PITCH R/A PCB MOUNT		Amphenol® Amphenol Corporation Amphenol Taiwan Corporation			
X.X ±0.20	CHECKED Roger Tsai	03/03/2014						
X.XXX ±0.10	APPROVED Arron Lin	03/03/2014						
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE PHD	UNIT mm	SCALE NA	SIZE A3	SHEET 1 OF 3	DWG No. G881AXX0X1TEU	REV. EX3
UNLESS OTHERWISE SPECIFIED								

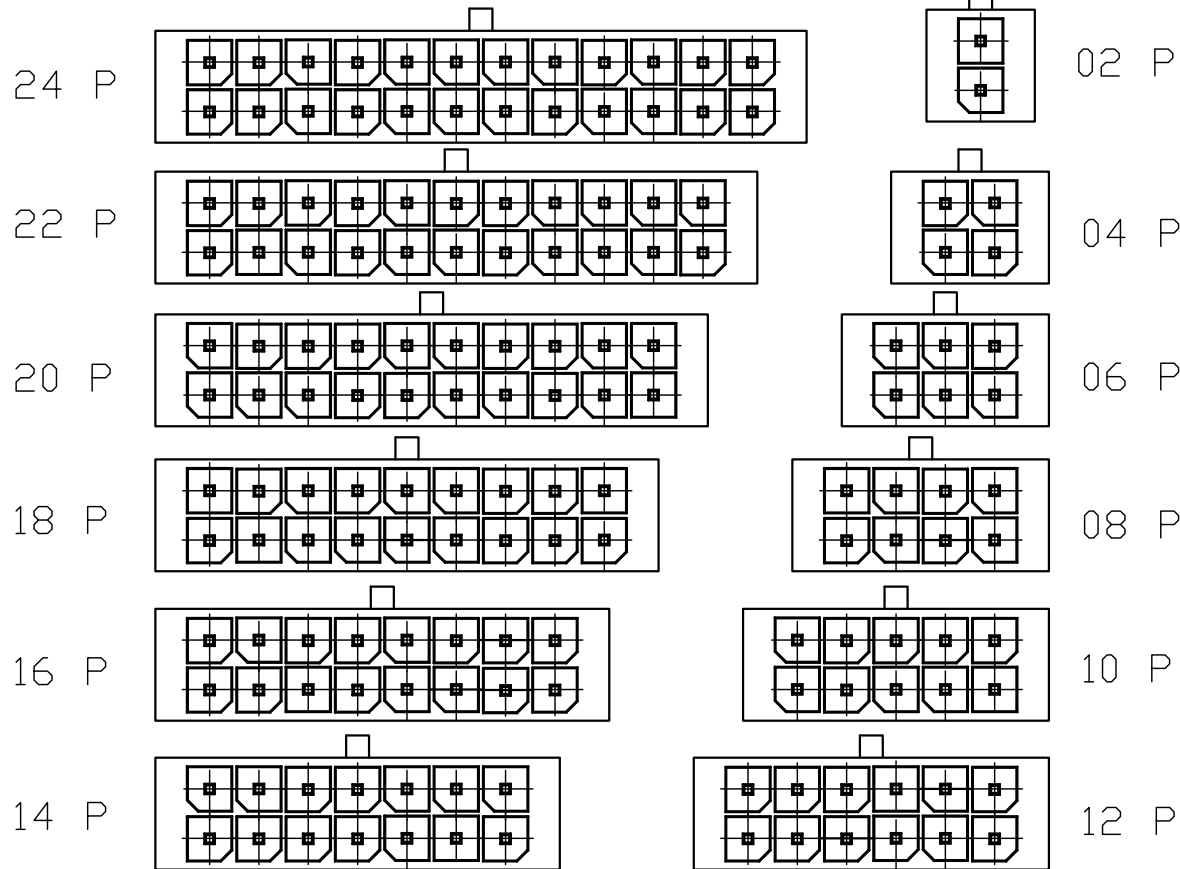
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EX3		UPDATE PACKING QUANTITY	03/03/2014	Arron Lin

02~24 PIN TOP VIEW

**PRELIMINARY RELEASE
SUBJECT TO CHANGE**



TOLERANCE		APPROVALS		DATE	TITLE		Amphenol® Amphenol Corporation Amphenol Taiwan Corporation		
X.		DRAWN	Debby Hung	03/03/2014	G881A SERIES WIRE TO BOARD, WAFER 3.00 MM PITCH R/A PCB MOUNT		UNIT	SIZE	PART No.
X.X	±0.30	CHECKED	Roger Tsai	03/03/2014			mm	A3	G881AXX0X1TEU
X.XX	±0.20	APPROVED	Arron Lin	03/03/2014			SCALE	SHEET	DWG No.
X.XXX	±0.10				NA		2 OF 3	G881AXX0X1TEU	REV. EX3
ANGULAR	±1°	DWG TYPE		PROJECT CODE					
UNLESS OTHERWISE SPECIFIED		CUST DWG		PHD					

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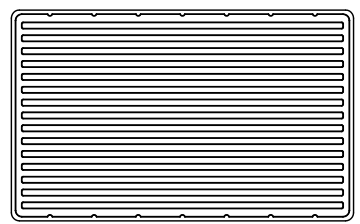
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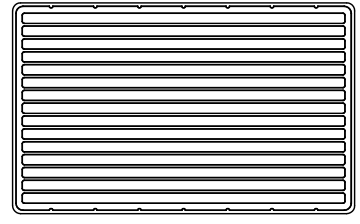
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426(L)*262.5(W)*10(H)

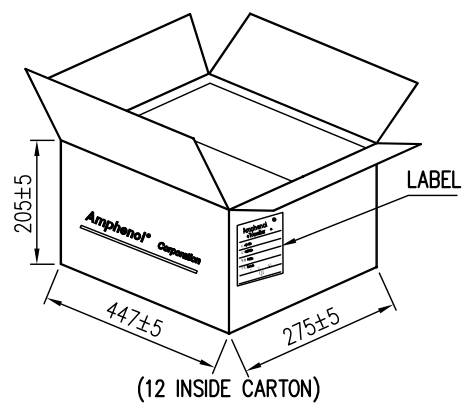
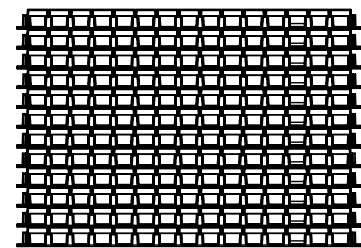
426(L)*262.5(W)*14(H)



TRAY BOTTOM COVER



TRAY TOP COVER



POS	PCS/TRAY	PCS/CARTON
02	900	10800
04	615	7380
06	465	5580
08	375	4500
10	315	3780
12	270	3240
14	240	2880
16	210	2520
18	180	2160
20	165	1980
22	150	1800
24	150	1800

- NOTE:
1. MATERIAL : BLACK CONDUCTIVE POLYSTYRENE ALLOY
 2. ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.
 3. THICKNESS : 0.80±0.05mm.

TOLERANCE		APPROVALS		DATE	TITLE		Amphenol® Amphenol Corporation Amphenol Taiwan Corporation		
X.		DRAWN Debby Hung		03/03/2014	G881A SERIES WIRE TO BOARD, WAFER 3.00 MM PITCH R/A PCB MOUNT		PART No. G881AXX0X1TEU		
X.X	±0.30	CHECKED Roger Tsai		03/03/2014					
X.XX	±0.20	APPROVED Arron Lin		03/03/2014					
X.XXX	±0.10	DWG TYPE CUST DWG		PROJECT CODE PHD	UNIT mm		SIZE A3	DWG No. G881AXX0X1TEU	
ANGULAR	±1°	UNLESS OTHERWISE SPECIFIED			SCALE NA		SHEET 3 OF 3	REV. EX3	